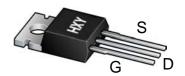


Description

The RFP50N06 uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of applications.



General Features TO-220C

 $V_{DS} = 60V, I_{D} = 60A$

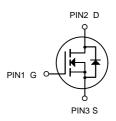
 $R_{DS(ON)} < 20 m \Omega$ @ $V_{GS}=10V$

Application

High efficiency switch mode power supplies

Power factor correction

Electronic lamp ballast



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Units Tube
RFP50N06	TO-220C	HXY MOSFET	50

Absolute Maximum Ratings@T_i=25°C(unless otherwise specified)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	60	V
VGS	Gate-Source Voltage	<u>+</u> 20	V
I _D @T _C =25°C	Drain Current	60	А
IDM	Pulsed Drain Current ¹	240	А
P _D @T _C =25°C	Total Power Dissipation	120	W
TSTG	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C



Electrical Characteristics (T_C=25°Cunless otherwise noted)

Parameter	Symbol Condition		Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage (Note 1)	BV _{DSS}	V _{GS} =0V I _D =250µA	60	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V	60	68	-	nA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics	· ·					
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS},I_{D}=250\mu A$	2.0	-	4.0	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =25A	-	17	20	mΩ
Forward Transconductance	g FS	V _{DS} =30V,I _D =40A	15	-	-	S
Dynamic Characteristics	· ·					
Input Capacitance	C _{lss}	\/ -05\/\/ -0\/	-	4050	-	PF
Output Capacitance	Coss	V_{DS} =25V, V_{GS} =0V , F=1.0MHz	-	430	-	PF
Reverse Transfer Capacitance	C _{rss}	, F-1.0IVID2	-	110	-	PF
Switching Characteristics	·			•		
Turn-on Delay Time	t _{d(on)}		-	60	-	nS
Turn-on Rise Time	t _r	V_{DD} =30V, I_D =40A	-	185	-	nS
Turn-Off Delay Time	t _{d(off)}	R_G =50 Ω (Note 2)	-	75	-	nS
Turn-Off Fall Time	t _f		-	60	-	nS
Total Gate Charge	Qg	V 20V/1 40A	-	39	-	nC
Gate-Source Charge	Q _{gs}	$V_{DS}=30V,I_{D}=40A,$ $V_{GS}=10V^{(Note\ 2)}$	-	9.3	-	nC
Gate-Drain Charge	Q _{gd}	V _{GS} -1UV	-	13	-	nC
Drain-Source Diode Characteristics	<u> </u>		•			
Diode Forward Voltage	V _{SD}	V _{GS} =0V,I _S =60A	-		1.5	V
Diode Forward Current (Note 2)	Is		-	-	60	Α

Notes:

^{1.} Repetitive Rating: Pulse width limited by maximum junction temperature.

^{2.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.



Typical Electrical

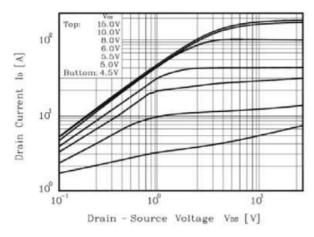


Figure 1. On Region Characteristics

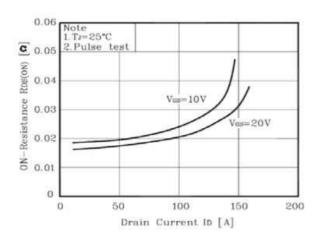


Figure 3. On Resistance Variation vs Drain Current and Gate Voltage

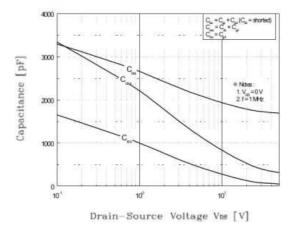


Figure 5. Capacitance Characteristics

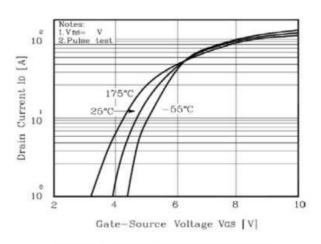


Figure 2. Transfer Characteristics

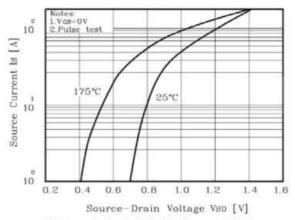


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

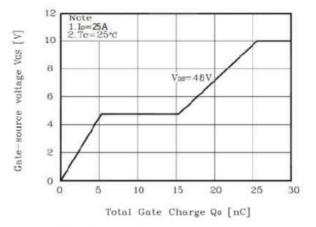


Figure 6. Gate Charge Characteristics



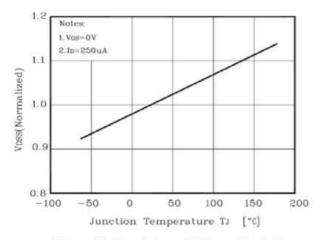


Figure 7. Breakdown Voltage Variation vs Temperature

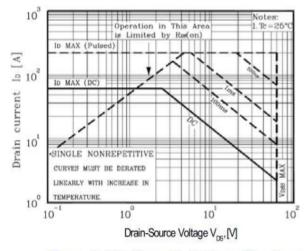


Figure 9. Maximum Safe Operating Area

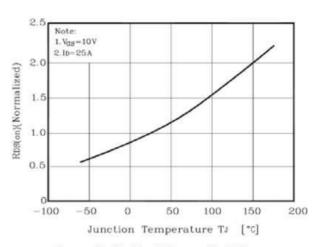


Figure 8. On-Resistance Variation vs Temperature

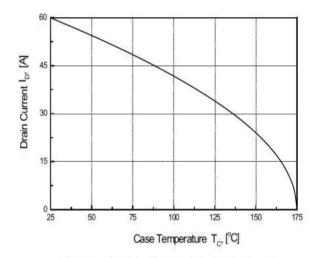


Figure 10. Maximum Drain Current vs Case Temperature

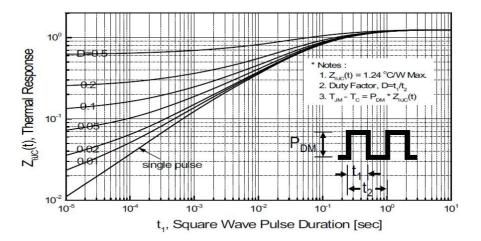
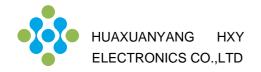
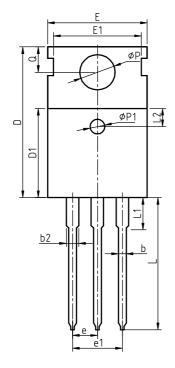
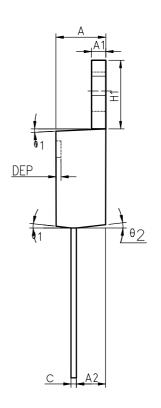


Figure 11. Transient Thermal Response Curve

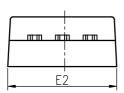


Package Information TO-220C





COMMON DIMENSIONS



SYMBOL	MIN	NOM	MAX	MIN	NOM	MAX
Α	4.40	4.57	4.70	0. 173	0.180	0.185
A1	1.27	1.30	1.33	0.050	0.051	0.052
A2	2.35	2.40	2.50	0.093	0.094	0.098
b	0.77	0.80	0.90	0.030	0.031	0.035
b2	1.17	1. 27	1.36	0.046	0.050	0.054
С	0.48	0.50	0.56	0.019	0.020	0.022
D	15.40	15.60	15.80	0.606	0.614	0.622
D1	9.00	9. 10	9. 20	0.354	0.358	0.362
DEP	0.05	0.10	0.20	0.002	0.004	0.008
E	9.80	10.00	10.20	0.386	0.394	0.402
E1	ı	8.70	ı	-	0.343	-
E2	9.80	10.00	10.20	0.386	0.394	0.402
е		2.54	BSC		0.100	BSC
e1		5.08	BSC		0.200	BSC
H1	6.40	6.50	6.60	0. 252	0.256	0.260
L	12.75	13.50	13.65	0.502	0.531	0.537
L1	-	3.10	3.30	-	0.122	0.130
L2		2.50	REF		0.098	REF
Р	3.50	3.60	3.63	0.138	0.142	0.143
P1	3.50	3.60	3.63	0.138	0.142	0.143
Q	2.73	2.80	2.87	0. 107	0.110	0. 113
θ 1	5°	7°	9°	5°	7°	9°
θ 2	1°	3°	5°	1°	3°	5°
θ 3	1°	3°	5°	1°	3°	5°

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